

Features

- Advanced Trench Process Technology
- Low Threshold Voltage
- Fast Switching Speed
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

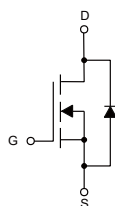
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature: -55°C to +150°C
- Thermal Resistance: 115°C/W Junction to Ambient (Note2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	0.34	A
		0.22	
Pulsed Drain Current (Note3)	I_{DM}	2	A
Total Power Dissipation (Note4)	P_D	1.08	W

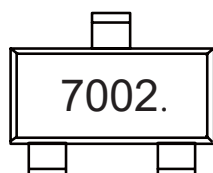
Note:

1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2 oz copper, in a still air environment with $T_A = 25^\circ\text{C}$.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

Internal Structure and Marking Code

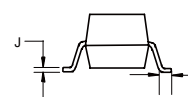
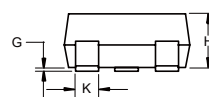
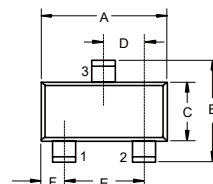


1. GATE
2. SOURCE
3. DRAIN



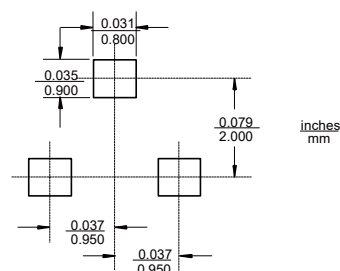
N-Channel MOSFET

SOT-23



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.110	0.120	2.80	3.04	
B	0.083	0.104	2.10	2.64	
C	0.047	0.055	1.20	1.40	
D	0.034	0.041	0.85	1.05	
E	0.067	0.083	1.70	2.10	
F	0.018	0.024	0.45	0.60	
G	0.0004	0.006	0.01	0.15	
H	0.035	0.043	0.90	1.10	
J	0.003	0.007	0.08	0.18	
K	0.012	0.020	0.30	0.51	
L	0.007	0.020	0.20	0.50	

Suggested Solder Pad Layout



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	60			V
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±10	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			80	nA
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.0	1.5	2.5	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =300mA		1.2	2.5	Ω
		V _{GS} =4.5V, I _D =200mA		1.3	3	
Forward Transconductance	g _{fs}	V _{DS} =10V, I _D =200mA	80	300		mS
Gate Resistance	R _g	f=1 MHz, Open drain		5		Ω
Diode Characteristics						
Continuous Body Diode Current	I _S				340	mA
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =300mA			1.2	V
Reverse Recovery Time	t _{rr}	I _F =0.34A, dI _F /dt=100A/μs		8.5		ns
Reverse Recovery Charge	Q _{rr}			8		nC
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =25V,V _{GS} =0V,f=1MHz		35		pF
Output Capacitance	C _{oss}			5		
Reverse Transfer Capacitance	C _{rss}			4		
Total Gate Charge	Q _g	V _{DS} =30V,V _{GS} =10V,I _D =0.34A		1.7		nC
Gate-Source Charge	Q _{gs}			0.5		
Gate-Drain Charge	Q _{gd}			0.3		
Turn-On Delay Time	t _{d(on)}	V _{DD} =30V, V _{GS} =10V, R _{GEN} =6Ω, I _{DS} =340mA		0.9		ns
Turn-On Rise Time	t _r			15		
Turn-Off Delay Time	t _{d(off)}			4.5		
Turn-Off Fall Time	t _f			33		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

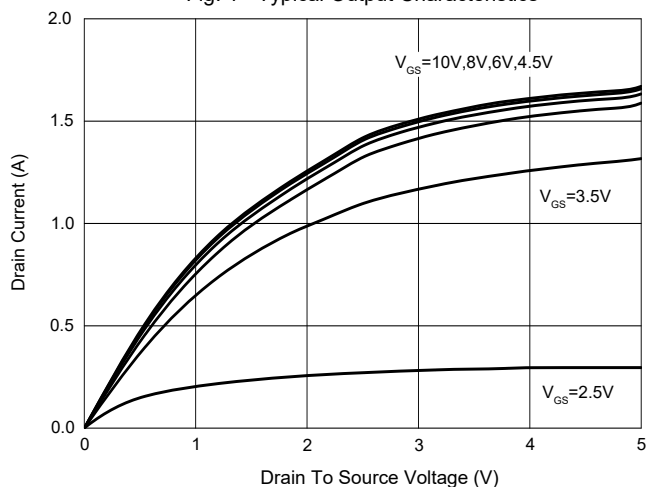


Fig. 2 - Transfer Characteristics

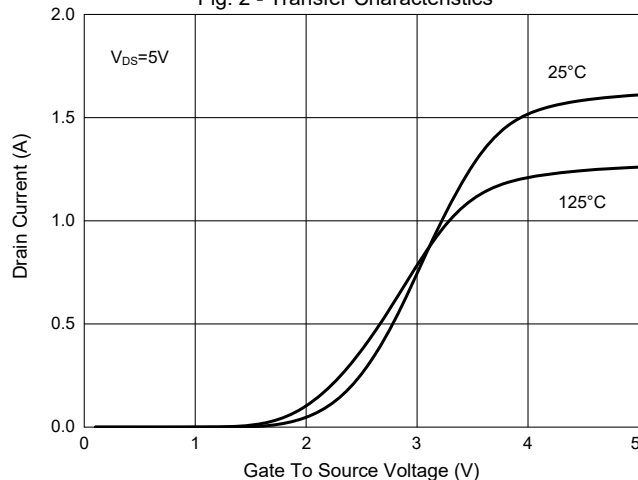


Fig.3 - $R_{DS(ON)}$ -- V_{GS}

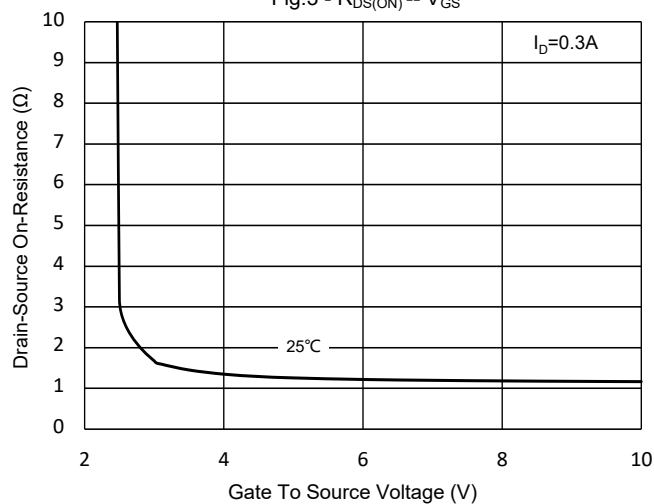


Fig. 4 - $R_{DS(ON)}$ -- I_D

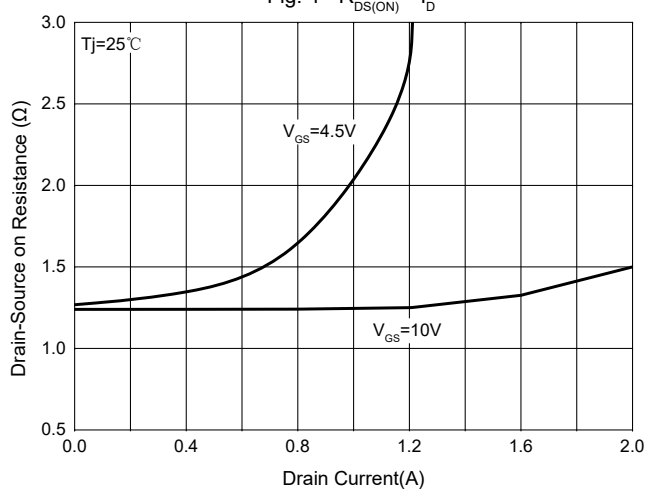


Fig. 5 - Capacitance Characteristics

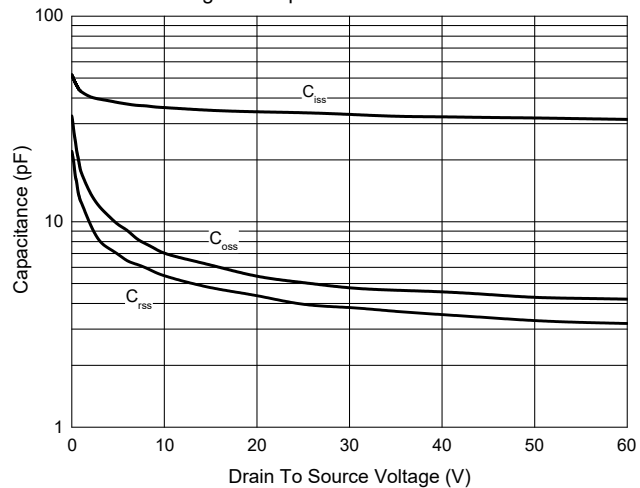
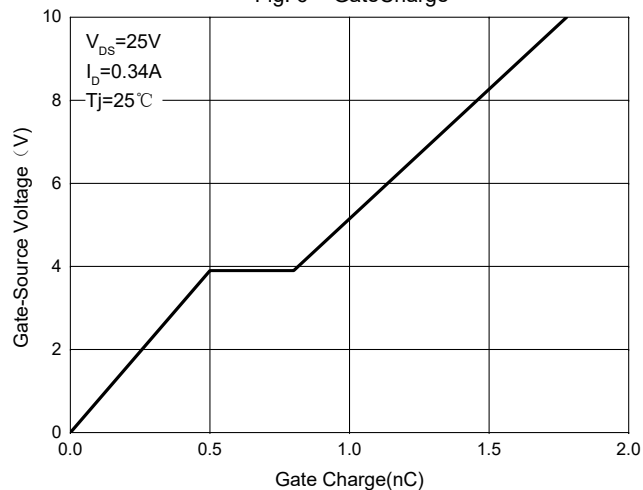


Fig. 6 - GateCharge



Curve Characteristics

Fig. 7 - Normalized Threshold Voltage

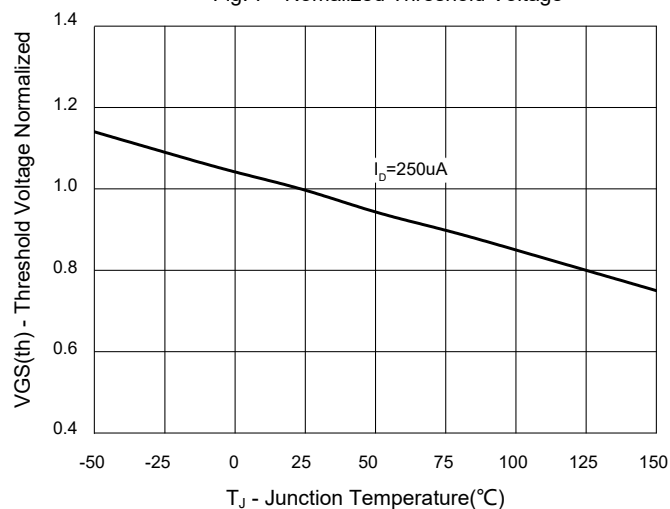


Fig.8-Normalized On Resistance Characteristics

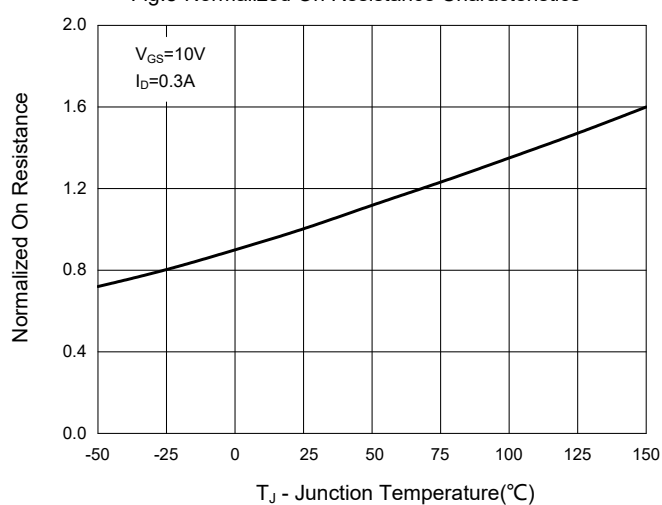


Fig. 9 - $I_S - V_{SD}$

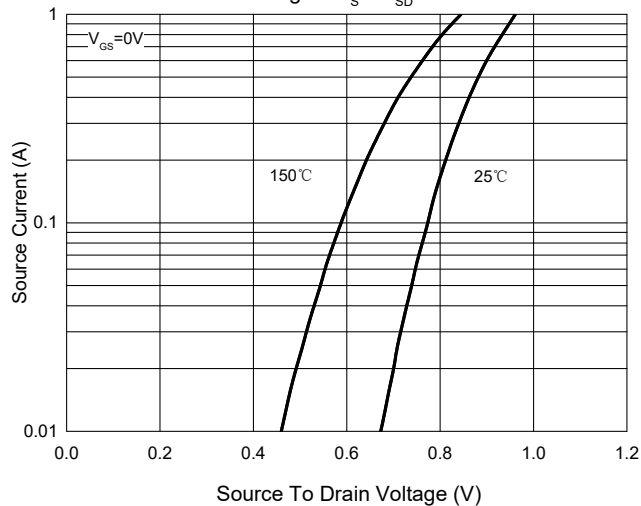


Fig. 10 - Drain Current

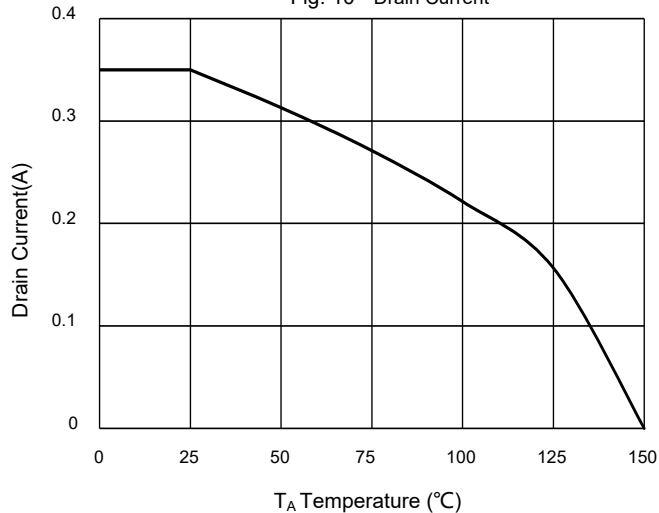
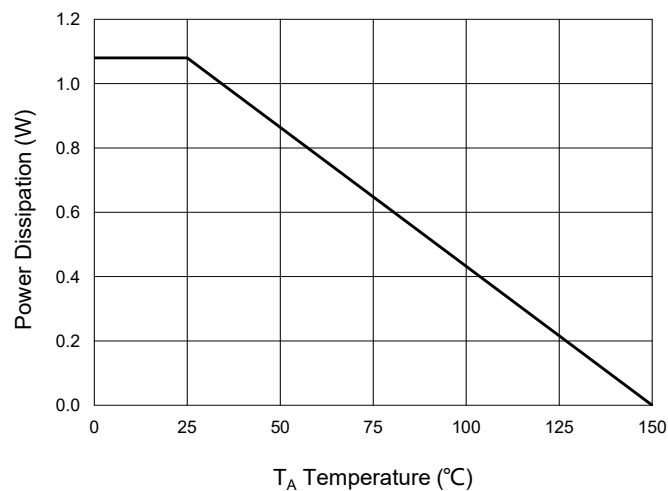


Fig. 11 - P_D Dissipation



Curve Characteristics

Fig.12 - Safe Operation Area

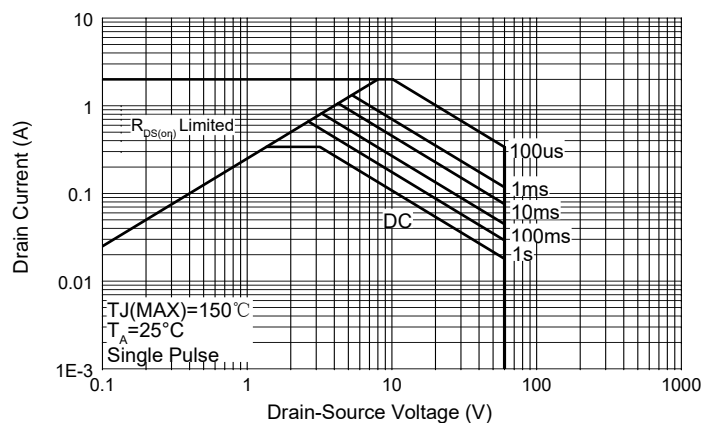
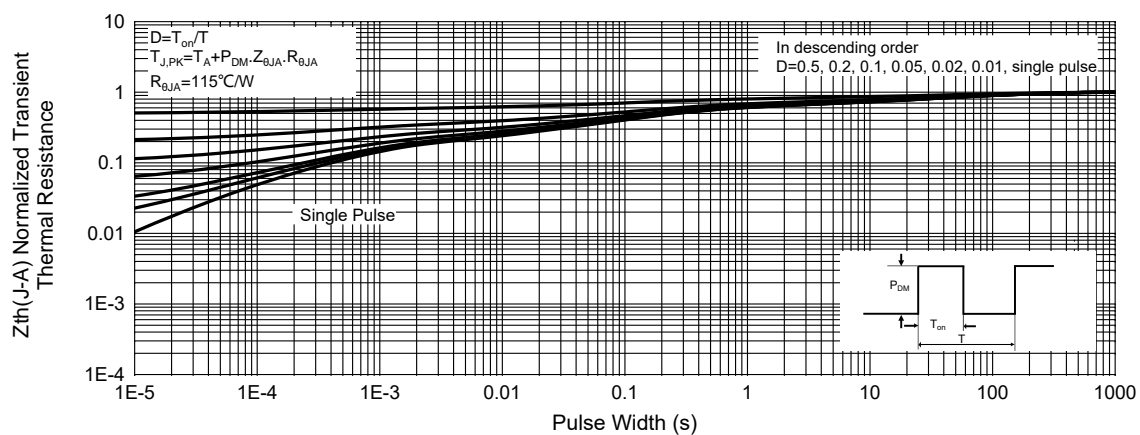


Fig.13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 3Kpcs/Reel
Part Number-13P	Tape&Reel: 10Kpcs/Reel

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